

This listing of claims will replace all prior versions and listings of claims in the application.

Listing of Claims:

1(currently amended). A multilayer RF module, comprising:
a plurality of vertically stacked ceramic layers including a first to a third ceramic layers,

wherein each of the first and the third ceramic layers has a circuit component thereon and the second ceramic layer is located between the first and the third ceramic layers and is provided with at least one or more air cavities filled with air, each of the air cavities being vertically aligned with the circuit components of the first and the third ceramic layers; wherein at least one of the air cavities is formed from a first surface of the second ceramic layer to a second surface thereof, the first surface being in contact with the first ceramic layer and the second surface being in contact with the third ceramic layer.

2(original). The multilayer RF module of claim 1, wherein the air cavities have a cylindrical shape.

3(original). The multilayer RF module of claim 2, wherein the air cavities have a diameter smaller than 100 to 500 μm .

4(original). The multilayer RF module of claim 1, wherein the circuit component is a metal pattern.

5(withdrawn). A method for fabricating a multilayer RF module, comprising the steps of:

preparing at least three green sheets;
forming at least one air cavity on one of said at least three green sheets;
forming a circuit components on each of two remaining green sheets;

stacking said at least three green sheets to thereby form a laminated green sheet structure, wherein the air cavity is located between the circuit components on said two remaining green sheets; and

pressing and sintering the laminated green sheet structure.

6(withdrawn). The method for fabricating a multilayer RF module of claim 5, wherein said at least one air cavity has a cylindrical shape.

7(withdrawn). The method for fabricating a multilayer RF module of claim 6, wherein the air cavity has a diameter smaller than about 100 to 500 μm .

8(withdrawn). The method for fabricating a multilayer RF module of claim 5, wherein the laminated green sheet structure pressing step is carried out at a temperature of about 70 °C and at a pressure of about 2500 - 2700 psi for about 10 min.

9(withdrawn). The method for fabricating a multilayer RF module of claim 5, wherein the circuit component is a metal pattern.

10(withdrawn). A method for fabricating the multilayer RF module of claim 1, comprising the steps of:

preparing at least three green sheets;

forming said at least one air cavity on one of said at least three green sheets;

forming the circuit components on each of two remaining green sheets;

stacking said at least three green sheets to thereby form a laminated green sheet structure, wherein the air cavity is located between the circuit components on said two remaining green sheets; and

pressing and sintering the laminated green sheet structure.